# Field Stop Trench IGBT 650 V, 40 A

## FGHL40T65MQDT

Field stop 4<sup>th</sup> generation mid speed IGBT technology copacked with full rated current diode.

#### **Features**

- Maximum Junction Temperature:  $T_J = 175^{\circ}C$
- Positive Temperature Co-efficient for Easy Parallel Operating
- High Current Capability
- Low Saturation Voltage:  $V_{CE(Sat)} = 1.45 \text{ V (Typ.)}$  @  $I_C = 40 \text{ A}$
- 100% of the Parts are Tested for I<sub>LM</sub> (Note 2)
- Smooth and Optimized Switching
- Tight Parameter Distribution
- RoHS Compliant

#### **Typical Applications**

- Solar Inverter
- UPS, ESS
- PFC, Converters

#### **MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Collector to Emitter Voltage		650	V
Gate to Emitter Voltage Transient Gate to Emitter Voltage		±20 ±30	V
Collector Current (Note 1) @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	I <sub>C</sub>	60 40	Α
Pulsed Collector Current (Note 2)	I <sub>LM</sub>	160	Α
Pulsed Collector Current (Note 3)	I <sub>CM</sub>	160	Α
Diode Forward Current (Note 1) @ $T_{C}$ = 25°C @ $T_{C}$ = 100°C	IF	60 40	Α
Pulsed Diode Maximum Forward Current	I <sub>FM</sub>	160	Α
Maximum Power Dissipation @ T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	P <sub>D</sub>	238 119	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C
Maximum Lead Temp. for Soldering Purposes (1/8" from case for 5 s)	T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

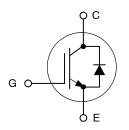
- 1. Value limit by bond wire
- 2.  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_{C}$  = 160 A, Inductive Load, 100% tested
- 3. Repetitive rating: pulse width limited by max. junction temperature



#### ON Semiconductor®

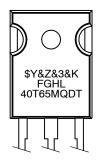
www.onsemi.com

40 A, 650 V V<sub>CESat</sub> = 1.45 V





#### MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = 3-Digit Date Code &K = 2-Digit Lot Traceability Code FGHL40T65MQDT = Specific Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
FGHL40T65MQDT	TO-247-3L	30 Units / Tube

#### THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal Resistance Junction-to-case, for IGBT	$R_{ heta JC}$	0.63	°C/W
Thermal Resistance Junction-to-case, for Diode	$R_{ heta JC}$	0.91	°C/W
Thermal Resistance Junction-to-ambient	$R_{ heta JA}$	40	°C/W

### **ELECTRICAL CHARACTERISTICS** (T<sub>.I</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				•		
Collector to Emitter Breakdown Voltage	$V_{GE} = 0 V$ , $I_C = 1 mA$	BV <sub>CES</sub>	650	-	-	V
Temperature Coefficient of Breakdown Voltage	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 1 mA	$\frac{\Delta BV_{CES}}{\Delta T_{J}}$	-	0.6	-	V/°C
Collector to Emitter Cut-off Current	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 650 V	I <sub>CES</sub>	_	-	250	μА
Gate Leakage Current	V <sub>GE</sub> = 20 V, V <sub>CE</sub> = 0 V	I <sub>GES</sub>	-	-	±400	nA
ON CHARACTERISTICS						_
Gate to Emitter Threshold Voltage	$V_{GE} = V_{CE}$ , $I_C = 40 \text{ mA}$	V <sub>GE(th)</sub>	3.0	4.5	6.0	V
Collector to Emitter Saturation Voltage	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 25°C V <sub>GE</sub> = 15 V, I <sub>C</sub> = 40 A, T <sub>J</sub> = 175°C	V <sub>CE(sat)</sub>	- -	1.45 1.65	1.8 -	V
DYNAMIC CHARACTERISTICS		•	-	-		
Input Capacitance	V <sub>CE</sub> = 30 V,	C <sub>ies</sub>	_	2680	_	pF
Output Capacitance	V <sub>GE</sub> = 0 V, f = 1 MHz	C <sub>oes</sub>	_	80	_	
Reverse Transfer Capacitance	1 1	C <sub>res</sub>	_	9	_	
Gate Charge Total	V <sub>CE</sub> = 400 V, I <sub>C</sub> = 40 A, V <sub>GE</sub> = 15 V	$Q_g$	_	80	_	nC
Gate to Emitter Charge		$Q_ge$	-	16	-	1
Gate to Collector Charge		$Q_{gc}$	_	19	_	1
SWITCHING CHARACTERISTICS, INDUC	TIVE LOAD					
Turn-on Delay Time	T <sub>J</sub> = 25°C,	t <sub>d(on)</sub>	_	16	_	ns
Rise Time	$V_{CC} = 400 \text{ V},$ $I_{C} = 20 \text{ A},$	t <sub>r</sub>	_	10	_	
Turn-off Delay Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$	t <sub>d(off)</sub>	_	82	_	
Fall Time	- GL 12 1	t <sub>f</sub>	_	51	_	1
Turn-on Switching Loss		E <sub>on</sub>	_	0.35	_	mJ
Turn-off Switching Loss		E <sub>off</sub>	_	0.25	_	1
Total Switching Loss		E <sub>ts</sub>	_	0.60	-	
Turn-on Delay Time	$T_J = 25^{\circ}C$ , $V_{CC} = 400 \text{ V}$ , $I_C = 40 \text{ A}$ ,	t <sub>d(on)</sub>	_	18	_	ns
Rise Time		t <sub>r</sub>	_	22	_	1
Turn-off Delay Time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	75	-	1
Fall Time	• GE - 10 V	t <sub>f</sub>	_	38	_	1
Turn-on Switching Loss		E <sub>on</sub>	-	0.88	-	mJ
Turn-off Switching Loss		E <sub>off</sub>	-	0.49	-	1
Total Switching Loss	1	E <sub>ts</sub>	_	1.36	_	1

## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, IND	UCTIVE LOAD	•		•		•
Turn-on delay time	T <sub>J</sub> = 175°C,	t <sub>d(on)</sub>	-	16	_	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 20 \text{ A},$	t <sub>r</sub>	-	11	_	
Turn-off delay time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	93	_	
Fall time	- GE	t <sub>f</sub>	-	88	-	
Turn-on switching loss		E <sub>on</sub>	-	0.64	-	mJ
Turn-off switching loss		E <sub>off</sub>	-	0.49	_	
Total switching loss		E <sub>ts</sub>	-	1.13	-	
Turn-on delay time	T <sub>J</sub> = 175°C,	t <sub>d(on)</sub>	-	16	-	ns
Rise time	$V_{CC} = 400 \text{ V},$ $I_{C} = 40 \text{ A},$	t <sub>r</sub>	-	26	-	
Turn-off delay time	$R_G = 6 \Omega$ , $V_{GE} = 15 V$	t <sub>d(off)</sub>	-	85	-	
Fall time		t <sub>f</sub>	-	75	-	
Turn-on switching loss		E <sub>on</sub>	-	1.31	-	mJ
Turn-off switching loss		E <sub>off</sub>	_	0.90	_	•
Total switching loss		E <sub>ts</sub>	-	2.21	-	
DIODE CHARACTERISTICS	•	-			•	
Diode Forward Voltage	I <sub>F</sub> = 40 A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.7	2.15	V
	I <sub>F</sub> = 40 A, T <sub>J</sub> = 175°C		-	1.65	-	
DIODE SWITCHING CHARACTERISTIC	CS, INDUCTIVE LOAD	-			•	
Reverse Recovery Energy	$T_J = 25^{\circ}C$ , $V_{CE} = 400 \text{ V}$ , $I_F = 20 \text{ A}$ ,	E <sub>rec</sub>	-	54	_	μЈ
Diode Reverse Recovery Time	di <sub>F</sub> /dt = 1000 A/μs	T <sub>rr</sub>	-	42	_	ns
Diode Reverse Recovery Charge		Q <sub>rr</sub>	-	329	-	nC
Diode Reverse Recovery Current		I <sub>rr</sub>	-	15	-	Α
Reverse Recovery Energy	T <sub>J</sub> = 25°C, V <sub>CE</sub> = 400 V, I <sub>F</sub> = 40 A,	E <sub>rec</sub>	-	121	-	μJ
Diode Reverse Recovery Time	di <sub>F</sub> /dt = 1000 A/μs	T <sub>rr</sub>	-	86	-	ns
Diode Reverse Recovery Charge		Q <sub>rr</sub>	-	665	-	nC
Diode Reverse Recovery Current		I <sub>rr</sub>	-	15	-	Α
Reverse Recovery Energy	$T_J = 175^{\circ}C$ , $V_{CE} = 400 \text{ V}$ , $I_F = 20 \text{ A}$ ,	E <sub>rec</sub>	-	360	-	μJ
Diode Reverse Recovery Time	di <sub>F</sub> /dt = 1000 A/μs	T <sub>rr</sub>	-	104	-	ns
Diode Reverse Recovery Charge	1	Q <sub>rr</sub>	-	1379	-	nC
Diode Reverse Recovery Current		I <sub>rr</sub>	-	27	-	Α
Reverse Recovery Energy	T <sub>J</sub> = 175°C, V <sub>CE</sub> = 400 V, I <sub>F</sub> = 40 A,	E <sub>rec</sub>	-	519	-	μJ
Diode Reverse Recovery Time	- di <sub>F</sub> /dt = 1000 A/μs	T <sub>rr</sub>	-	141	-	ns
Diode Reverse Recovery Charge		Q <sub>rr</sub>	-	1877	_	nC
Diode Reverse Recovery Current	$\neg$	I <sub>rr</sub>	_	26	_	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

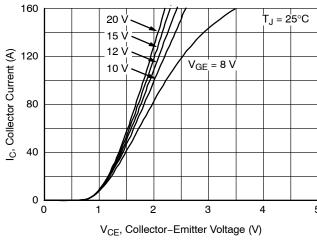


Figure 1. Typical Output Characteristics (T<sub>J</sub> = 25°C)

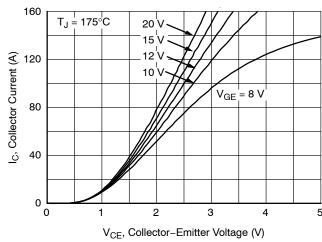


Figure 2. Typical Output Characteristics ( $T_J = 175^{\circ}C$ )

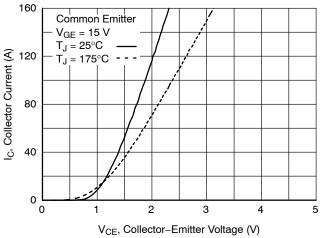


Figure 3. Typical Saturation Voltage Characteristics

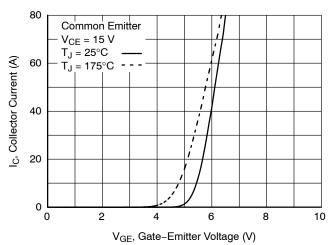


Figure 4. Typical Transfer Characteristics

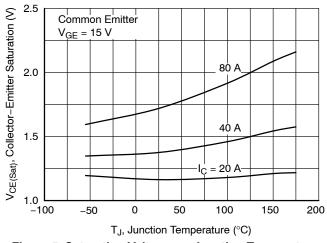


Figure 5. Saturation Voltage vs. Junction Temperature

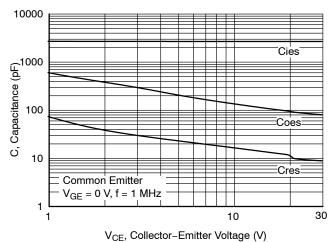


Figure 6. Capacitance Characteristics

#### TYPICAL CHARACTERISTICS (continued)

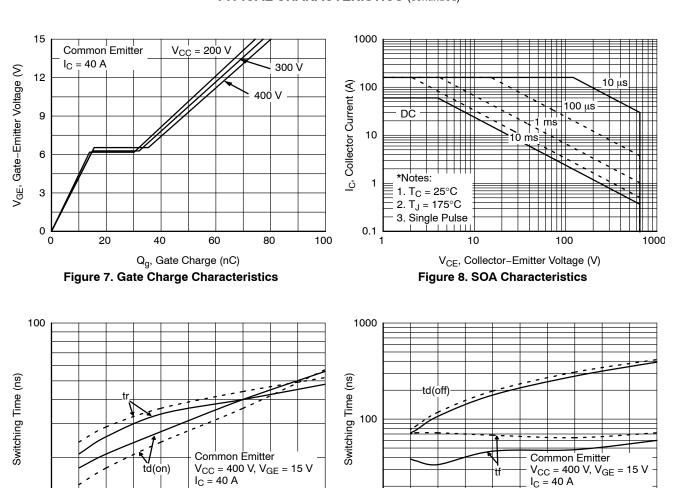


Figure 9. Turn-on Characteristics vs. Gate Resistance

 $R_q$ , Gate Resistance ( $\Omega$ )

20

10

10

 $T_J = 25^{\circ}C$ 

30

 $T_{J}^{-} = 175^{\circ}C$  - - -

40

Figure 10. Turn-off Characteristics vs. Gate Resistance

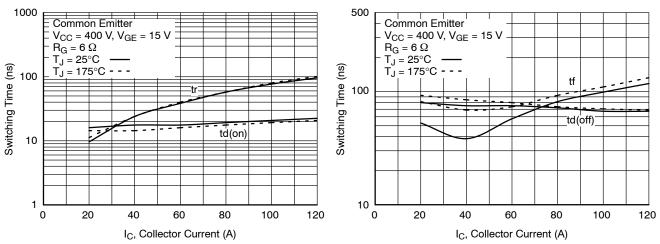
 $R_q$ , Gate Resistance ( $\Omega$ )

20

 $\tilde{T_J} = 25^{\circ}C$ 

 $T_{J}^{-} = 175^{\circ}C^{-} - -$ 

50



10

50

10

Figure 11. Turn-on Characteristics vs. Collector Current Figure 12. Turn-off Characteristics vs. Collector Current

#### TYPICAL CHARACTERISTICS (continued)

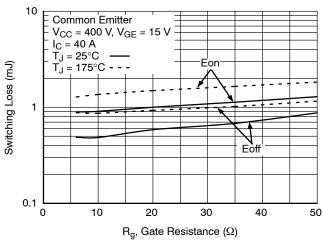


Figure 13. Switching Loss vs. Gate Resistance

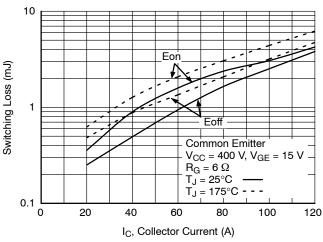


Figure 14. Switching Loss vs. Collector Current

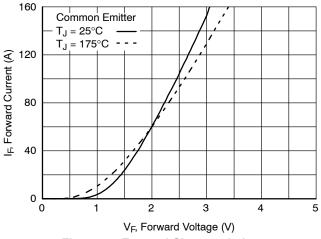


Figure 15. Forward Characteristics

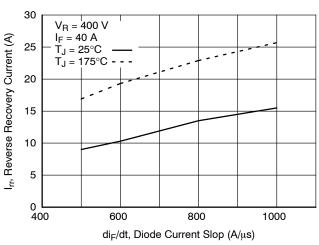


Figure 16. Reverse Recovery Current

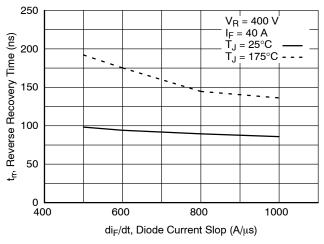


Figure 17. Reverse Recovery Time

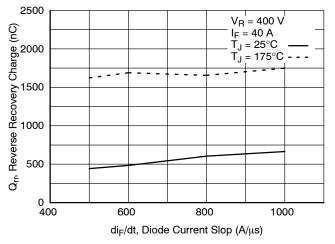


Figure 18. Stored Charge

#### TYPICAL CHARACTERISTICS (continued)

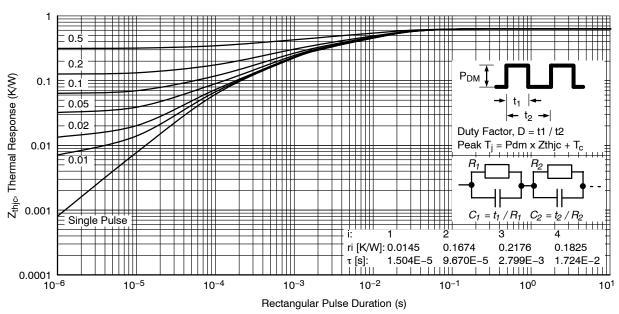


Figure 19. Transient Thermal Impedance of IGBT

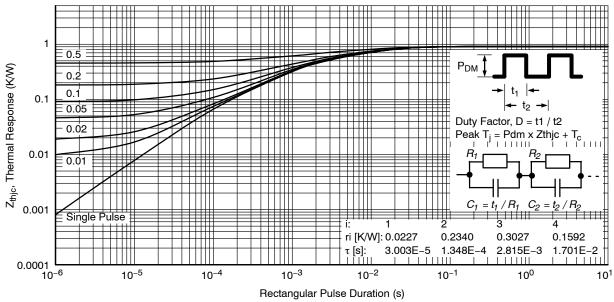
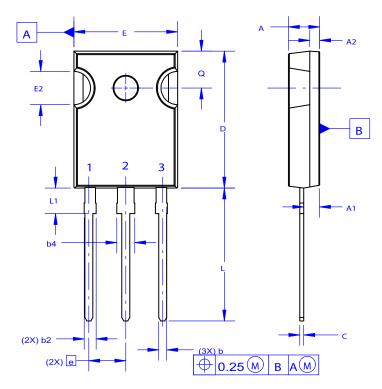


Figure 20. Transient Thermal Impedance of Diode

#### **PACKAGE DIMENSIONS**

TO-247-3LD CASE 340CX **ISSUE A** 

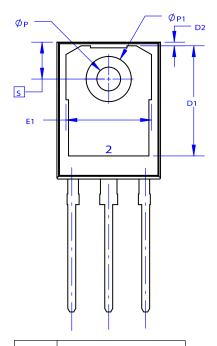


#### NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

  B. ALL DIMENSIONS ARE IN MILLIMETERS.

- C. DRAWING CONFORMS TO ASME Y14.5 2009.
  D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	4.58	4.70	4.82	
<b>A</b> 1	2.20	2.40	2.60	
A2	1.40	1.50	1.60	
D	20.32	20.57	20.82	
Е	15.37	15.62	15.87	
E2	4.96	5.08	5.20	
е	?	5.56	~	
L	19.75	20.00	20.25	
L1	3.69	3.81	3.93	
ØΡ	3.51	3.58	3.65	
Q	5.34	5.46	5.58	
S	5.34	5.46	5.58	
b	1.17	1.26	1.35	
b2	1.53	1.65	1.77	
b4	2.42	2.54	2.66	
С	0.51	0.61	0.71	
D1	13.08	~	~	
D2	0.51	0.93	1.35	
E1	12.81	~	~	
Ø P1	6.60	6.80	7.00	

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AFGY160T65SPD-B4 IGW30N60TP IGW40N60TP IGW50N60TP IHW30N65R5 IKFW40N60DH3E IKP15N65H5 IKQ100N60T

IKQ120N60T IKW30N65WR5 IKW75N60H3 IKZ50N65NH5 IKZ75N65NH5 FGD3040G2-F085C FGH4L50T65SQD FGHL40T65MQDT

FGHL50T65MQD FGHL50T65MQDTL4 FGHL75T65LQDT FGHL75T65MQD FGHL75T65MQDT FGHL75T65MQDTL4

FGY75T120SWD EL3120S1(TA)(SAS)-V IHW15N120E1 IKQ75N120CS6 IKW50N65WR5 SL15T65FK KGF50N65KDF-U/H

IHFW40N65R5S IKW08N120CS7XKSA1 IKQ75N120CH3 IHW30N160R5 SGM100HF12A1TFD CRG50T60AK3SD CRG40T60AN3S